Product Change Notification

112472 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**112472 - 00**
Change Title:	**Selected Intel® Celeron® Processors and Intel® Core ™ i3, i5 and i7 Processors PCN 112472-00, Label**
Date of Publication:	**August 05, 2013**

Key Characteristics of the Change:

Label

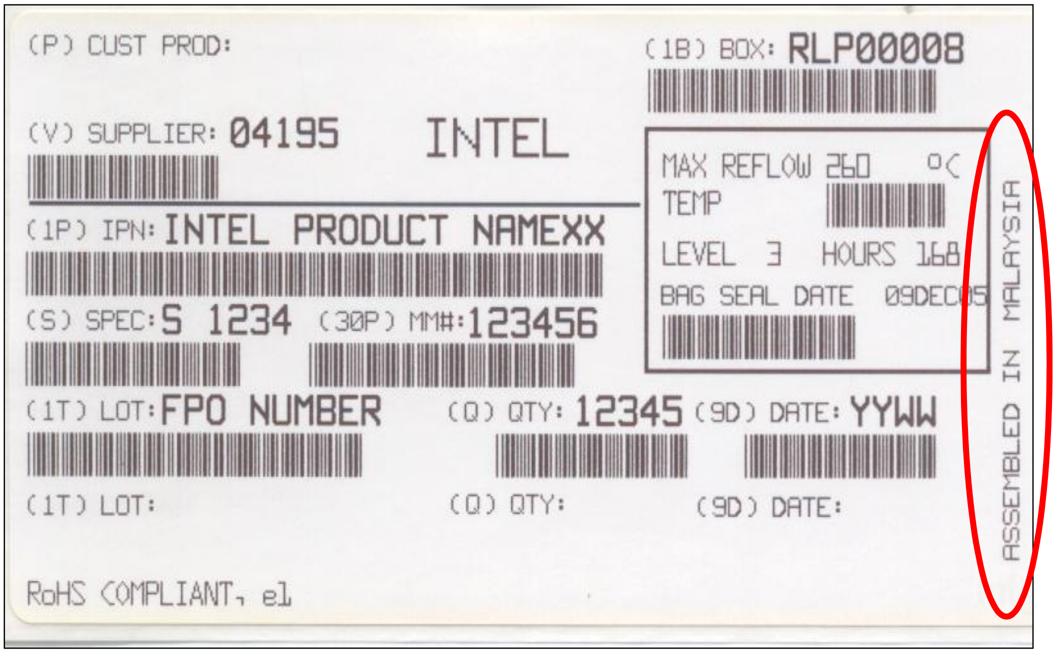
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 01, 2013

Description of Change to the Customer:

In line with manufacturing site consolidation, Intel is transferring the products listed in the products affected table from Chengdu assembly site to Penang assembly site. This consolidation will enable Intel to provide better support to customers in the dynamic market environment.

The intermediate box label will reflect this change (see image below).



(P) CUST PROD:
(1B) BOX: RLP00008
(V) SUPPLIER: 04195 INTEL
MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 09DEC05
(1P) IPN: INTEL PRODUCT NAMEXX
(S) SPEC: S 1234 (30P) MM#: 123456
(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW
(1T) LOT: (Q) QTY: (9D) DATE:
RoHS COMPLIANT, e1
ASSEMBLED IN MALAYSIA

Customer Impact of Change and Recommended Action:

The new manufacturing site has been certified equivalent (form, fit, function, and reliability) for the affected products and technologies of this change. Customers may receive product from either site until existing inventory is depleted. There will be no change to the product order code.

Products Affected / Intel Ordering Codes:

Product Code	S-Spec	MM#
CP80617003981AH	S LBTQ	907993
CP80617004119AE	S LBU3	907996
CP80617004803AA	S LBUX	908002
CN80617004458AC	S LBXJ	908569
CN80617004467AH	S LBXW	908570
CN80617004461AC	S LBXK	908571
CN80617004545AG	S LBXG	908572
CN80617006201AA	S LBWX	908573
CN80617004455AC	S LBXH	908574
CN80617005745AC	S LBXX	908575
CN80617006204AA	S LBWV	908576

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
August 5, 2013	00	Originally Published PCN